



**THE DATASHEET OF
B39431B3757U310**





SAW Components

Data Sheet B3757





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B3757

Low-loss Filter

434,42 MHz

Data Sheet

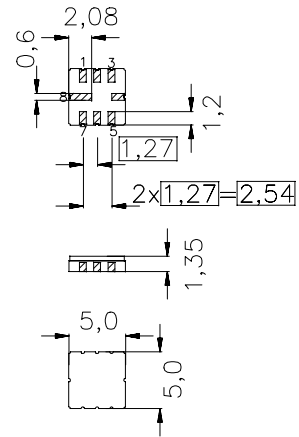
Ceramic package **QCC8C**

Features

- RF low-loss filter for remote control receivers
- Package for **Surface Mounted Technology (SMT)**
- Balanced and unbalanced operation possible
- Passivation layer: Protec

Terminals

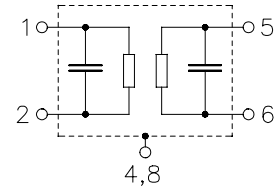
- Ni, gold plated



typ. dimensions in mm, approx. weight 0,1 g

Pin configuration

- 1 Input Ground
- 2 Input
- 5 Output
- 6 Output Ground
- 4,8 Case - Ground
- 3,7 to be grounded



Type	Ordering code	Marking and package according to	Packing according to
B3757	B39431-B3757-U310	C61157-A7-A56	F61074-V8070-Z000

Electrostatic Sensitive Device (ESD)

Maximum ratings

Operable temperature range	T_A	-45/+120	°C	source impedance 50 Ω
Storage temperature range	T_{stg}	-45/+120	°C	
DC voltage	V_{DC}	6	V	
Source power	P_S	10	dBm	



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Characteristics

Reference temperature: $T_A = -40 \dots +95^\circ\text{C}$
 Terminating source impedance: $Z_S = 50 \Omega$ and matching network
 Terminating load impedance: $Z_L = 50 \Omega$ and matching network

		min.	typ.	max.	
Center frequency (center frequency between 3 dB points)	f_c	—	434,42	—	MHz
Minimum insertion attenuation (including losses in matching network)	α_{\min}				
434,26 ... 434,58 MHz		—	2,0	3,0	dB
Pass band (relative to α_{\min})					
434,26 ... 434,58 MHz		—	0,5	2,0	dB
434,24 ... 434,60 MHz		—	0,7	3,0	dB
434,20 ... 434,64 MHz		—	1,0	6,0	dB
Pass bandwidth					
$\alpha_{\text{rel}} \leq 3 \text{ dB}$		0,64	0,70	0,76	MHz
Relative attenuation (relative to α_{\min})	α_{rel}				
10,00 ... 414,50 MHz		55	62	—	dB
414,50 ... 425,00 MHz		48	55	—	dB
425,00 ... 432,22 MHz		31	35	—	dB
432,22 ... 432,62 MHz		39	44	—	dB
432,62 ... 433,60 MHz		8	11	—	dB
435,42 ... 442,50 MHz		10	14	—	dB
442,50 ... 550,00 MHz		36	44	—	dB
550,00 ... 700,00 MHz		55	60	—	dB
700,00 ... 805,00 MHz		40	45	—	dB
805,00 ... 1000,00 MHz		60	70	—	dB
Impedance for pass band matching ²⁾					
Input: $Z_{\text{IN}} = R_{\text{IN}} \parallel C_{\text{IN}}$		—	310 \parallel 2,2	—	$\Omega \parallel \text{pF}$
Output: $Z_{\text{OUT}} = R_{\text{OUT}} \parallel C_{\text{OUT}}$		—	310 \parallel 2,2	—	$\Omega \parallel \text{pF}$

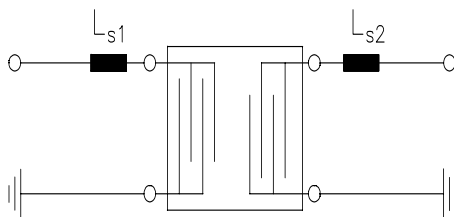
²⁾ Impedance for passband matching bases on an ideal, perfect matching of the SAW filter to source- and to load impedance (here 50 Ohm). After the SAW filter is removed and input impedance into the input matching / output matching network is calculated.

The conjugate complex value of these characteristic impedances are the input and output impedances for flat passband. For more details, we refer to EPCOS application note #4.



Data Sheet

Matching network to 50 Ω (element values depend on pcb layout and equivalent circuit)



$$L_{s1} = 39 \text{ nH}$$

$$L_{s2} = 39 \text{ nH}$$

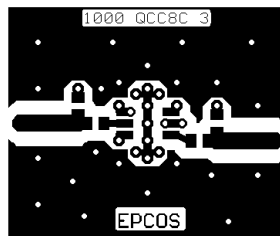
Minimising the crosstalk

For a good ultimate rejection a low crosstalk is necessary. Low crosstalk can be realised with a good RF layout. The major crosstalk mechanism is caused by the “ground-loop” problem.

Grounding loops are created if input- and output transducer GND are connected on the top-side of the PCB and fed to the system grounding plane by a common via hole. To avoid the common ground path, the ground pin of the input- and output transducer are fed to the system ground plane (bottom PCB plane) by their own via hole. The transducers' grounding pins should be isolated from the upper grounding plane.

A common GND inductivity of 0.5nH degrades the ultimate rejection (crosstalk) by 20dB.

The optimised PCB layout, including matching network for transformation to 50 Ohm, is shown here. In this PCB layout the grounding loops are minimised to realise good ultimate rejection.



Optimised PCB layout for SAW filters in QCC8C package, pinning 2,5 (top side, scale 1:1)

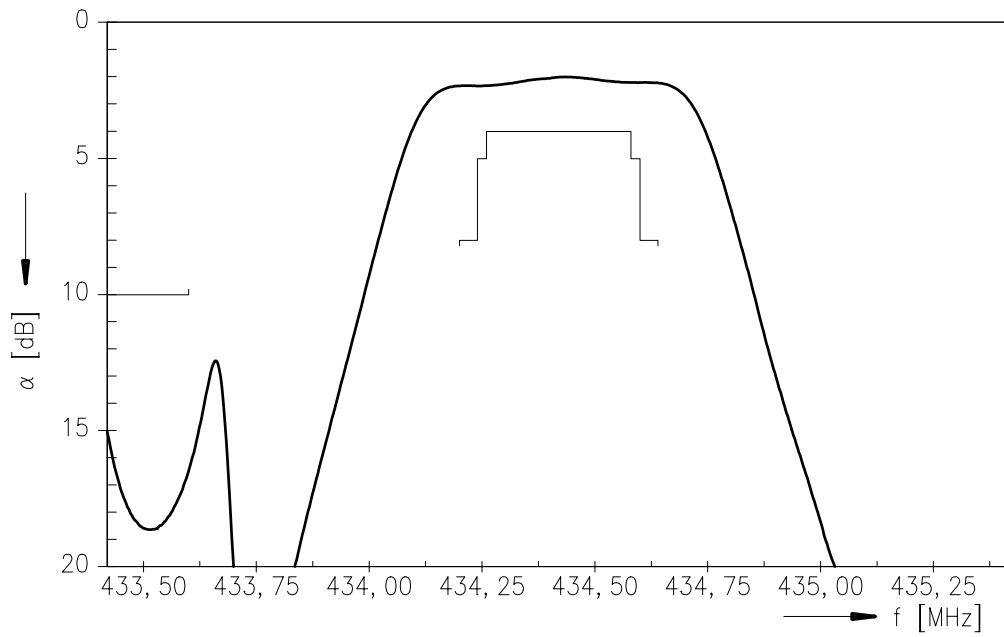
The bottom side is a copper plane (system ground area). The input and output grounding pins are isolated and connected to the common ground by separated via holes.

For good contact of the upper grounding area with the lower side it is necessary to place enough via holes.

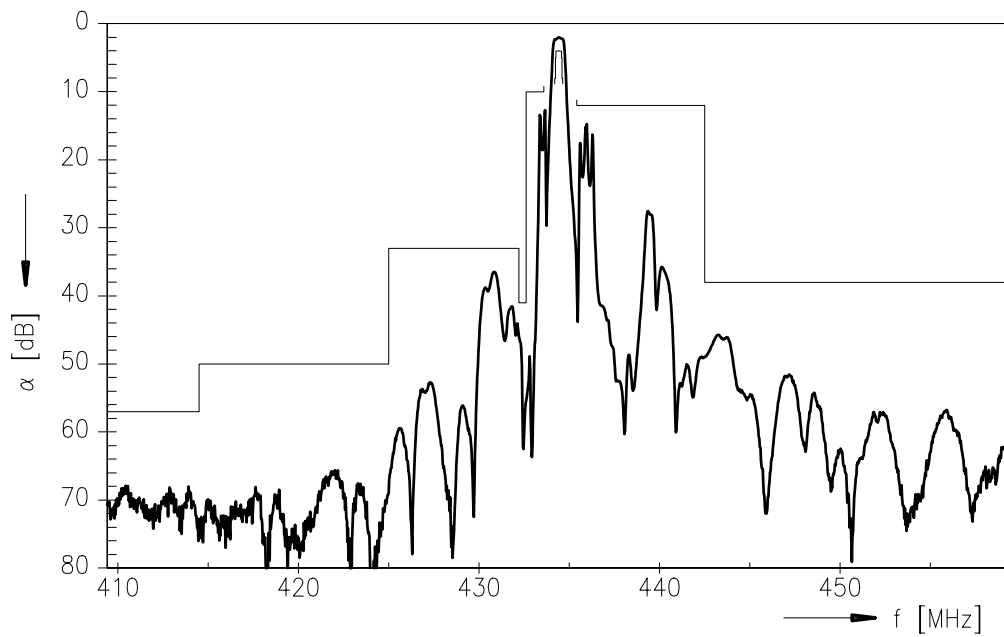


Data Sheet

Frequency response



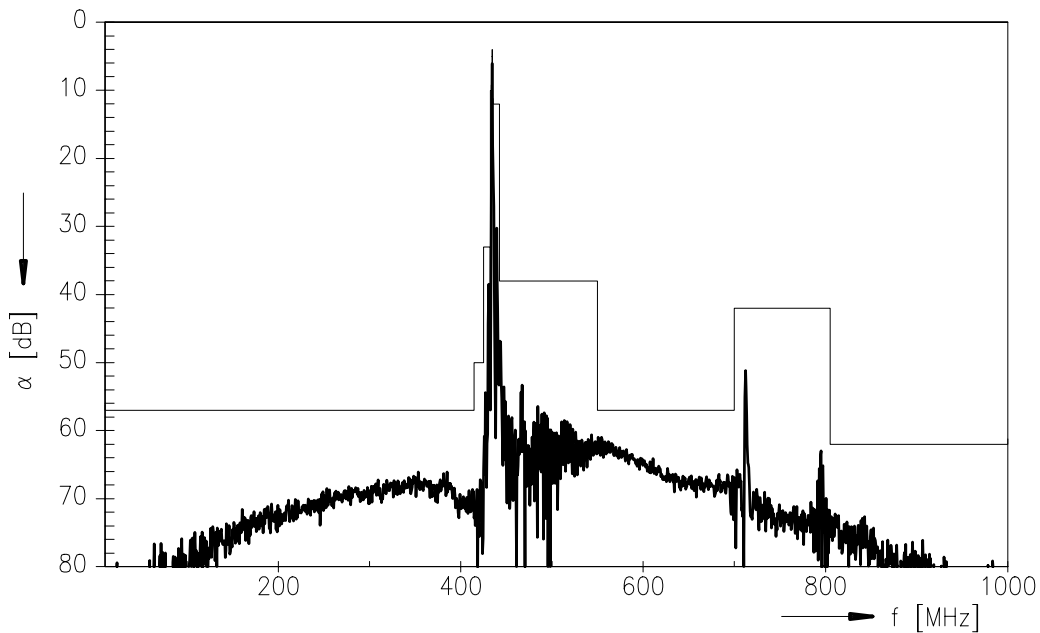
Frequency response (wideband)





Data Sheet

Frequency response (ultimate rejection)



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